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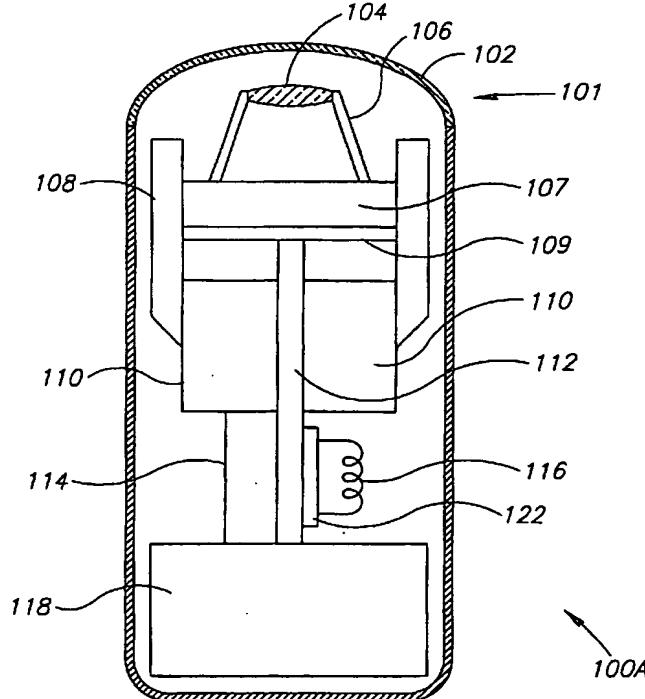
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(54) Title: REDUCED SIZE IMAGING DEVICE



(57) Abstract: A reduced diameter in vivo imaging device, such as a swallowable imaging capsule. The imaging device includes a first circuit board configured for accommodating at least an image sensor, and a second circuit board, which is in electrical communication with the first circuit board and which extends substantially perpendicularly from the bottom surface of the first circuit board.

WO 2004/028336 A2